

Amendments to the ClaimsIn The Claims:

Please cancel restricted Claims 1-8 and unrestricted Claim 13 without prejudice and amend Claims 9, 12, 15, 27, and 29-31 such that the Claims read as follows:

1-8. (Cancelled)

9. (Currently Amended) An apparatus for rinsing and drying a substrate, comprising:

a tank of fluid, for at least partially submerging a substrate, the tank comprising a first portion for receiving the substrate and a second portion that is horizontally adjacent the first portion, wherein the first portion is operatively coupled to the second portion such that the substrate may be passed directly from the first portion to the second portion without being removed from the tank; and

a lift mechanism for lifting the substrate from the second portion of the tank.

10. (Original) The apparatus of claim 9, further comprising a substrate shuttle operatively coupled within the tank for receiving the substrate within the first portion and for shuttling the substrate to the second portion.

11. (Original) The apparatus of claim 9, further comprising:

a drying vapor source positioned to supply drying vapors to an air/substrate/fluid interface formed as

the substrate is lifted from the second portion of the tank by the lifting mechanism.

12. (Currently Amended) A method for rinsing and drying a substrate comprising:

at least partially submerging a substrate in a first portion of a tank of fluid;

shuttling the substrate directly from the first portion of the tank of fluid to a second portion of the tank of fluid without removing the substrate from the tank; and

lifting the substrate from ~~a~~ the second portion of the tank of fluid that is horizontally adjacent the first portion of the tank of fluid.

13. (Canceled)

14. (Original) The method of claim 12, further comprising supplying drying vapor to an air/substrate/fluid interface formed as the substrate is lifted from the second portion of the tank of fluid.

15. (Currently Amended) An apparatus for rinsing and drying a substrate comprising:

a tank of cleaning fluid, for submerging a substrate, the tank comprising a first portion for receiving and cleaning the substrate and a second portion, operatively coupled to the first portion, for rinsing the substrate, the first and second portions being horizontally adjacent;

a lifting mechanism operatively coupled to the tank for lifting a substrate from the cleaning fluid;

a drying vapor source positioned to supply drying vapors to the air/substrate/rinsing fluid interface; and

a substrate shuttle operatively coupled within the tank for receiving the substrate within the first portion and for shuttling the substrate directly to the second portion without removing the substrate from the tank.

16. (Original) The apparatus of claim 15, wherein the apparatus further comprises a drying enclosure operatively coupled above the second portion of the tank for receiving substrates therefrom, wherein the drying enclosure encloses the drying vapor source.

17. (Original) The apparatus of claim 16 further comprising:

a lifting mechanism for lifting a substrate from the substrate shuttle to the drying enclosure.

18. (Original) The apparatus of claim 16 further comprising a mechanism adapted to hold the wafer in a fixed position relative to the drying enclosure.

19. (Original) The apparatus of claim 16 wherein the drying enclosure further comprises a side wall having a sealable opening for substrate extraction.

20. (Original) The apparatus of claim 9 wherein the first portion of the tank comprises a transducer adapted to sonically clean a substrate.

21. (Original) The apparatus of claim 10 wherein the first portion of the tank comprises a transducer adapted to sonically clean a substrate.

22. (Original) The apparatus of claim 11 wherein the first portion of the tank comprises a transducer adapted to sonically clean a substrate.

23. (Original) The method of claim 12 further comprising cleaning the substrate in the first portion of the tank.

24. (Original) The method of claim 12 further comprising cleaning the substrate in the second portion of the tank.

25. (Original) The method of claim 12 further comprising cleaning the substrate in the first and second portion of the tank.

26. (Original) The method of claim 14 further comprising cleaning the substrate in the first portion of the tank.

27. (Currently Amended) The method of claim ~~13~~ 12 further comprising cleaning the substrate in the first portion of the tank.

28. (Original) The method of claim 14 further comprising cleaning the substrate in the second portion of the tank.

29. (Currently Amended) The method of claim ~~13~~
12 further comprising cleaning the substrate in the second
portion of the tank.

30. (Currently Amended) The method of claim ~~13~~
12 further comprising cleaning the substrate in the first
and second portion of the tank.

31. (Currently Amended) The method of claim ~~13~~
12 further comprising cleaning the substrate in the first
and second portion of the tank.

32. (Original) The apparatus of claim 15 wherein
the first portion of the tank comprises a transducer
adapted to sonically clean the substrate.

33. (Original) The apparatus of claim 16 wherein
the first portion of the tank comprises a transducer
adapted to sonically clean the substrate.

34. (Original) The apparatus of claim 17 wherein
the first portion of the tank comprises a transducer
adapted to sonically clean the substrate.

35. (Original) The apparatus of claim 18 wherein
the first portion of the tank comprises a transducer
adapted to sonically clean the substrate.

36. (Original) The apparatus of claim 19 wherein
the first portion of the tank comprises a transducer
adapted to sonically clean the substrate.